

# UltraPort™ SFP+

## Low Cost, Compact And Flexible SFP28 Interconnect System

Amphenol ICC's UltraPort™ SFP+ interconnect system comprises of a 20-position hot swappable I/O connector enclosed in a metal cage mounted to a host PCB. It supports 28Gb/s applications with a backward compatibility for next generation ethernet and fibre Channel applications. UltraPort™ SFP+ connector shares the same unique mating interface and EMI cage dimensions as the SFP+ form factor.

The cages are built to use with several board thicknesses and assembly processes to accommodate server and switch applications for cost optimized solutions. The connector accepts multiple transceivers per INF-8081 to combine, transmit, and receive functions in a low cost, compact and flexible format. Stacked versions (2XN) consist of a 2-row cage with integrated connectors. A wide variety of cage configurations, with a two-piece construction and enhanced transceiver mating tabs are offered in press-fit or solder tail versions.

- Electrical interface employs 1 lane that operates up to 28Gb/s per channel
- UltraPort™ SFP+ connector shares the same unique mating interface and EMI cage dimensions as the SFP+ form factor
- UltraPort™ SFP+ connector accepts multiple transceivers per INF-8081 to combine, transmit, and receive functions in a low cost, compact and flexible format

### FEATURES

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- UltraPort™ SFP+ connector accepts multiple transceivers per INF-8081



### TARGET MARKETS



### BENEFITS

- Support next generation Ethernet and Fibre Channel applications
- Support previous generation systems
- Support various application requirements

## TECHNICAL INFORMATION

### MATERIAL

- Housing: Black color, Glass reinforced, Lead Free Solder Reflow Process Compatible Thermo Plastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin or gold flash options
- Plating Mating Area: Gold
- Resonance Dampening Feature: Conductive Polymer

### MECHANICAL PERFORMANCE

- Durability: 250 mating cycles
- Mating Force: 40 N max.
- Contact Normal Force: 0.3 N min./PIN
- PCB Thickness Single Side Mount (Cage): 1.57 mm (0.062 in.)
- PCB Thickness Belly to Belly (Cage): 3.00 mm (0.118 in.)
- Unmating Force (Cage): 12.5 N max.
- Insertion Force to PCB (Cage):
  - 1000 N for 2 port
  - 2100 N for 4 port
  - 3000 N for 6 port

### ELECTRICAL PERFORMANCE

- Operating Voltage: 30 VDC per contact
- Operating Current: 0.5 A per contact
- Differential Impedance: 100Ω +/- 10Ω

### ENVIRONMENTAL

- Operating and (Storage) Temperature: -55° to +85°C
- RoHS & Halogen-Free

### TOOLING INFORMATION

- Configurations:
  - 1xN (N = 1, 2, 3, 4, 5, 6, 8)
  - 2xN (N = 1, 2, 4, 5, 6, 8, 12)

### TARGET MARKETS/APPLICATIONS



Cellular Infrastructure  
Telecommunications Hardware



Servers  
Storage



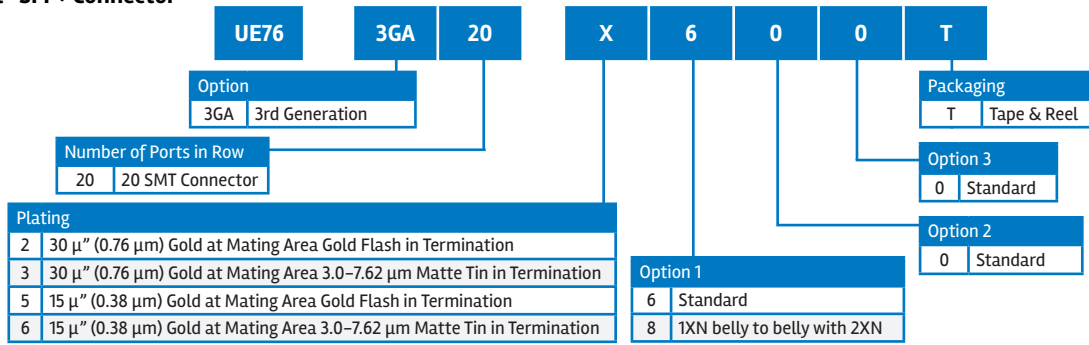
Test and Measurement Equipment



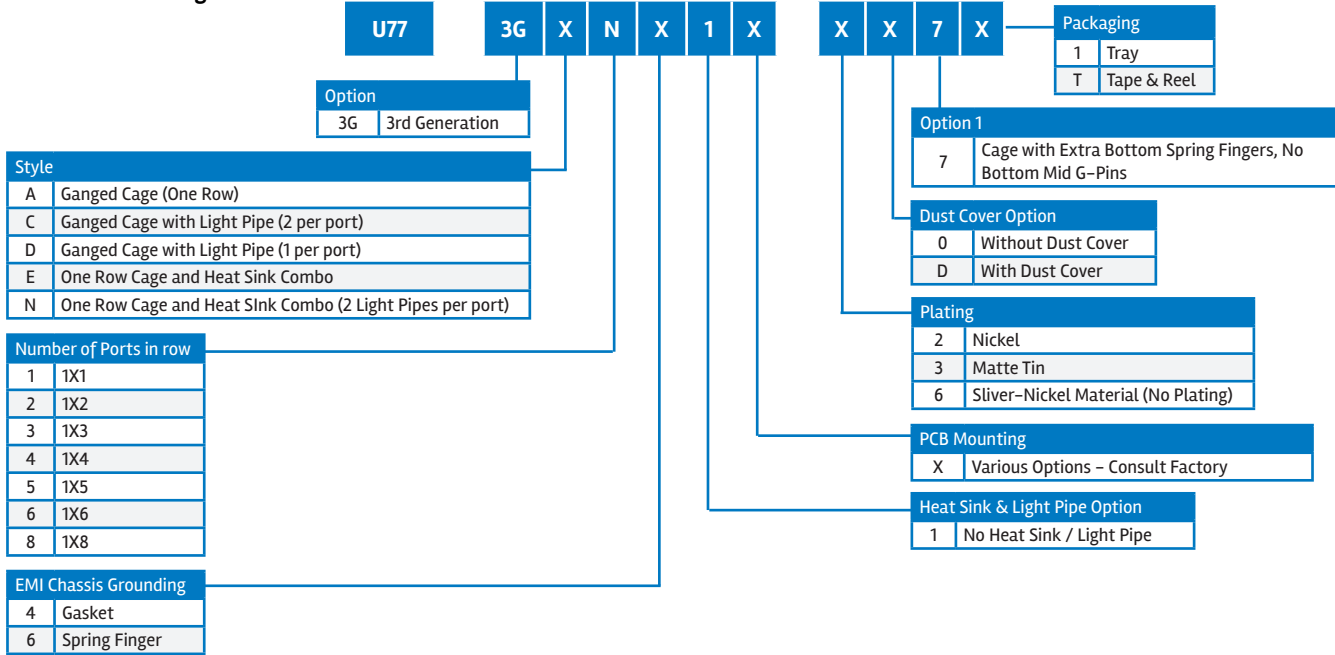
Medical Diagnostic Equipment

# UltraPort™ SFP+

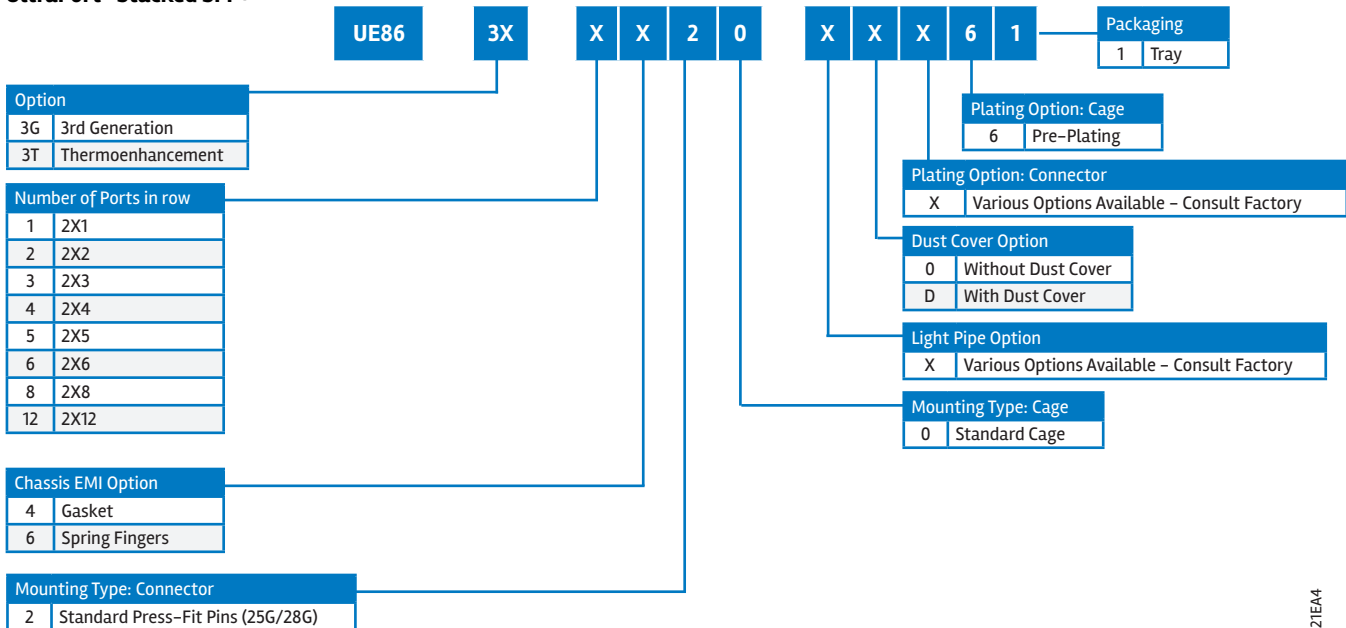
## UltraPort™ SFP+ Connector



## UltraPort™ SFP+ Cage



## UltraPort™ Stacked SFP+



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